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U.S. UTILITY Patent Application

PATENT NUMBER and  
ISSUE DATE

APPL NUM 10052089	FILING DATE 01/16/2002	CLASS 324	SUBCLASS 180.5	GAU 2862	EXAMINER Stoner
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\*\*APPLICANTS: Seshan Krishna; Singh Kuljeet;

\*\*CONTINUING DATA VERIFIED: none KS

\*\* FOREIGN APPLICATIONS VERIFIED: none KS

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	
Foreign priority claimed <input type="checkbox"/> yes <input checked="" type="checkbox"/> no		ATTORNEY DOCKET NO	
35 USC 119 conditions met <input type="checkbox"/> yes <input checked="" type="checkbox"/> no		884.659US1	
Verified and Acknowledged Examiners's initials <i>Kuljeet KS</i>			
TITLE : Wire-bond process flow for copper metal-silicon structures achieved thereby, and testing method			

U.S. DEPT. OF COMM. / PAT. & TM. PTO-436L (Rev. 12-81)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drawn	Figs. Drawn
		Print Fig.	
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
		PREPARED FOR ISSUE	
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